

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	Doped silicon	Silicon (Si)	7440-21-3	1.61585	100.0	1.9
				Subtotal	1.61585	100
Wire	Impurity	Non hazardous		0.00001	0.01	0.00001
	Pure metal	Copper (Cu)	7440-50-8	0.08929	99.99	0.10499
				Subtotal	0.0893	100
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.02596	0.05	0.03053
	Copper alloy	Zinc (Zn)	7440-66-6	0.05192	0.1	0.06105
	Copper alloy	Iron (Fe)	7439-89-6	1.19416	2.3	1.40415
	Copper alloy	Copper (Cu)	7440-50-8	50.64789	97.55	59.55427
				Subtotal	51.91993	100
Post-plating	Lead alloy	Tin (Sn)	7440-31-5	0.48476	100.0	0.57
				Subtotal	0.48476	100
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	0.68797	1.5	0.80895
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	4.35715	9.5	5.12335
	Filler	Silica fused	60676-86-0	40.36096	88.0	47.4584
	Carbon Black	Carbon black	1333-86-4	0.45865	1.0	0.5393
				Subtotal	45.86473	100
Die Attach		Aromatic Polyester Resin	60088-52-0	0.00064	2.5	0.00075
		Paraffin wax	8002-74-2	0.00178	7.0	0.00209
		Epoxy resin system		0.00509	20.0	0.00598
		Silver (Ag)	7440-22-4	0.01793	70.5	0.02108
				Subtotal	0.02544	100
				Total	100.00001	100
						117.5849

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